

## CMOS Quad Clocked "D" Latch

High-Voltage Types (20-Volt Rating)

CD4042B types contain four latch circuits, each strobed by a common clock. Complementary buffered outputs are available from each circuit. The impedance of the n- and p-channel output devices is balanced and all outputs are electrically identical. Information present at the data input is transferred to outputs Q and  $\overline{Q}$  during the CLOCK level which is programmed by the POLARITY input. For POLARITY = 0 the transfer occurs during the 0 CLOCK level and for POLARITY = 1 the transfer occurs during the 1 CLOCK level. The outputs follow the data input providing the CLOCK and POLARITY levels defined above are present. When a CLOCK transition occurs (positive for POLARITY = 0 and negative for POLARITY = 1) the information present at the input during the CLOCK transition is retained at the outputs until an opposite **CLOCK** transition occurs.

The CD4042B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffixes), 16-lead dual-in-line plastic package (E suffix), 16-lead small-outline packages (D, DR, DT, DW, DWR, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

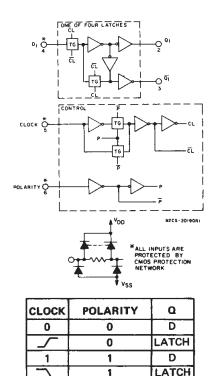


Fig. 1 - Logic block diagram and truth table.

#### Features:

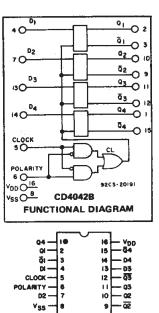
- Clock polarity control Q and Q outputs
- **Common clock**
- Low power TTL compatible
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1  $\mu$ A at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings Noise margin (over full package temperature range):

  - 1 V at VDD = 5 V
  - 2 V at V<sub>DD</sub> = 10 V 2.5 V at V<sub>DD</sub> = 15 V
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices'

#### Applications:

- Buffer storage
- Holding register
- General digital logic

STATIC ELECTRICAL CHARACTERISTICS



CD4042B Types

VIEW 92CS-20756R

TERMINAL ASSIGNMENT

TOP

CHARAC											
TERISTIC	CONDITIONS			LIMITS AT INDICATED TE							UNITS
	Vo	VIN	V <sub>DD</sub>						+25		
	(V)	(V)	(V)	-55	40	+85	+125	Min.	Түр.	Max.	
Quiescent	_	0,5	5	1	1	30	30	— ·	0.02	1	
Device	_	0,10	10	2	2	60	60	_	0.02	2	μA
Current	-	0,15	15	4	4	120	120	—	0.02	4	<i>~</i> ^
I <sub>DD</sub> Max.	-	0,20	20	20	20	600	600	—	0.04	20	
Output Low											
(Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_	
Current,	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	·	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	mA
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_	
Current,	9.5	0,10	10	-1.6	-1.5	-1.1	0.9	-1.3	-2.6	. —	
IOH Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	6.8	· · · · -	
Output Volt-											
age:	_	0,5	5		0.0	)5			_0	0.05	
Low-Level,		0,10	10		0.0	)5		-	0	0.05	
V <sub>OL</sub> Max.	—	0,15	15		0.0	)5		-	0	0.05	v
Output Volt-											Ť
age:	_	0,5	5	1. 1. j.	4.9	95		4.95	5	_	
High-Level,	_	0,10	10		9.9	95		9.95	10	-	
V <sub>OH</sub> Min.	-	0,15	15		14.	95		14.95	15	1	
Input Low	0.5,4.5	-	5		1.			· _	_	1.5	
Voltage,	1,9	_	10				· · ·	· _	—	3	
V <sub>IL</sub> Max.	1.5,13.5		15		4	F .		-	-	4	
Input High	0.5,4.5	_	5		3.	5		3.5		_	ľ
Voltage,	1,9	_	10		7	f -		7			
V <sub>IH</sub> Min.	1.5,13.5	-	15		1	1		11	-	-	
Input Current, I <sub>IN</sub> Max.	_	0,18	18	±0.1	±0.1	±1	±1	-	±10-5	±0.1	μA

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MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to V <sub>SS</sub> Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	
DC INPUT CURRENT, ANY ONE INPUT	
POWER DISSIPATION PER PACKAGE (PD):	
For $T_A = -55^{\circ}C$ to $+100^{\circ}C$	
For T <sub>A</sub> = +100°C to +125°C Derate DEVICE DISSIPATION PER OUTPUT TRANSISTOR	Linearity at 12mW/°C to 200mW
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	
OPERATING-TEMPERATURE RANGE (TA)	
STORAGE TEMPERATURE RANGE (Tstg)	
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 $\pm$ 1/32 inch (1.59 $\pm$ 0.79mm) from case for 10s max	+265°C

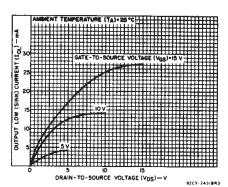
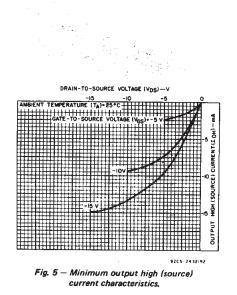
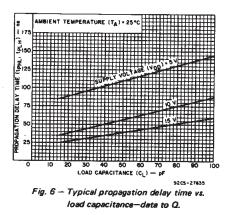


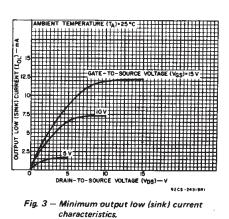
Fig. 2 – Typical output low (sink) current characteristics.

RECOMMENDED OPERATING CONDITIONS at  $T_A = 25^{\circ}C$ , Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	VDD	LIN	UNITS		
	(V)	Min.	Max.		
Supply-Voltage Range (For T <sub>A</sub> =Full Package Temperature Range)	-	3	18	v	
Clock Pulse Width, t <sub>W</sub>	5 10 15	200 100 60	- - -	ns	
Setup Time, t <sub>S</sub>	5 10 15	50 30 25		ns	
Hold Time, t <sub>H</sub>	5 10 15	120 60 50	-  -	ns	
Clock Rise or Fall Time: t <sub>r</sub> , t <sub>f</sub>	5,10 15	Not rise or fall time sensitive.		μS	







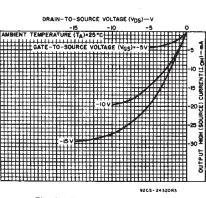
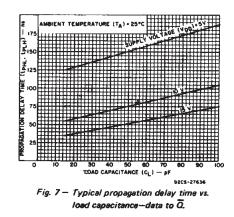


Fig. 4 — Typical output high (source) current characteristics.



COMMERCIAL CMOS HIGH VOLTAGE ICS

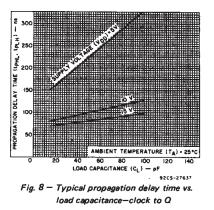
3

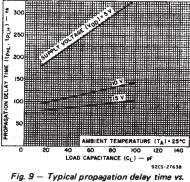
### CD4042B Types

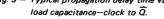
DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = 25^{\circ}C$ ; input  $t_r$ ,  $t_f = 20$  ns,  $C_L = 50$  pF,

R<sub>L</sub> = 200 KΩ

CHARACTERISTIC	VDD	LIN	UNITS		
	(V)	Тур.	Max.	1	
Propagation Delay	5	110	220		
Time: tpHL , tpLH	10	55	110	ns	
Data In to Q	15	40	80		
	5	150	300		
Data In to Q	10	75	150	ns	
	15	50	100		
	5	225	450		
Clock to Q	10	100	200	ns	
	15	80	160		
a	5	250	500		
Clock to Q	10	115	230	ns	
	15	90	180		
Transition	5	100	200	`	
Time : tTHL, tTLH	10	50	100	ns	
	15	40	80		
Minimum Clock	5	100	200		
Pulse Width, tw	10	50	100	ns	
	15	30	60		
	5	60	120		
Minimum Hold Time, t <sub>H</sub>	10	30	60	ns	
	15	25	50		
Minimum Setup	5	0	50		
Time, t <sub>S</sub>	10	0	30	ns	
	15	0	25		
Clock Input Rise or Fall	5,10	Not rise or fall			
Time: t <sub>r</sub> , t <sub>f</sub>	15	time se	μS		
Input Capacitance, C <sub>IN</sub>		_		<u> </u>	
Polarity Input	-	5	7.5	pF	
All Other Inputs		7.5	15	pF	







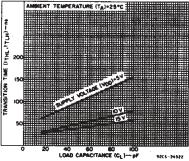


Fig. 11 — Typical transition time vs. load capacitance.

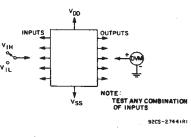
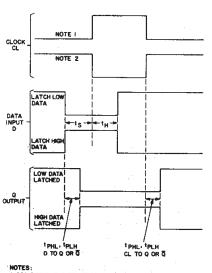
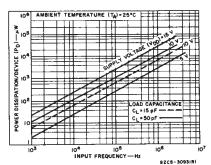


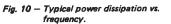
Fig. 14 - Input voltage test circuit.

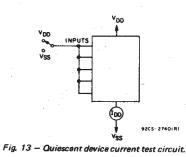


NOTES: 1. FOR POSITIVE CLOCK EDGE, INPUT DATA IS LATCHED WHEN POLARITY IS LOW. 2. FOR NEGATIVE CLOCK EDGE, INPUT DATA IS LATCHED WHEN POLARITY IS NIGH.

92cs-27630 Fig. 12 - Dynamic test parameters.







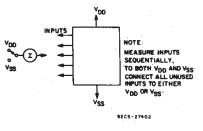
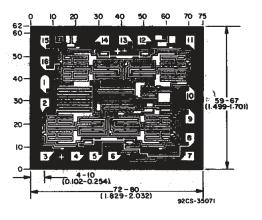


Fig. 15 – Input current test circuit.

#### **Chip Dimensions and Pad Layout**



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils  $(10^{-3} \text{ inch})$ .

1. S. 1. S.

North States (States)

COMMERCIAL CMOS HIGH VOLTAGE ICS

3-115

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



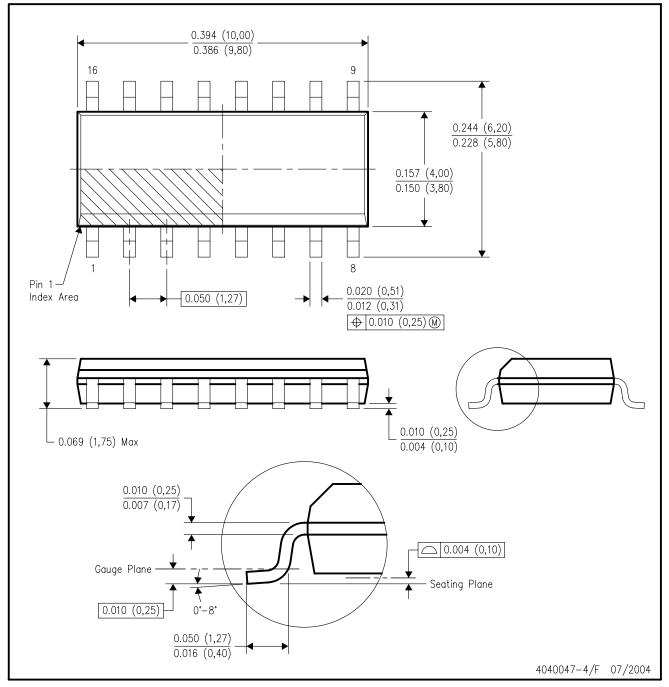
NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

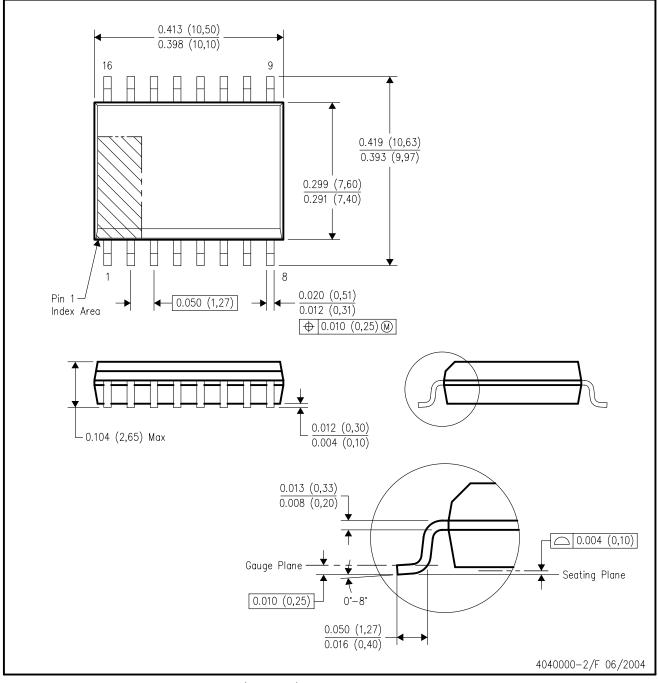
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AA.



## MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



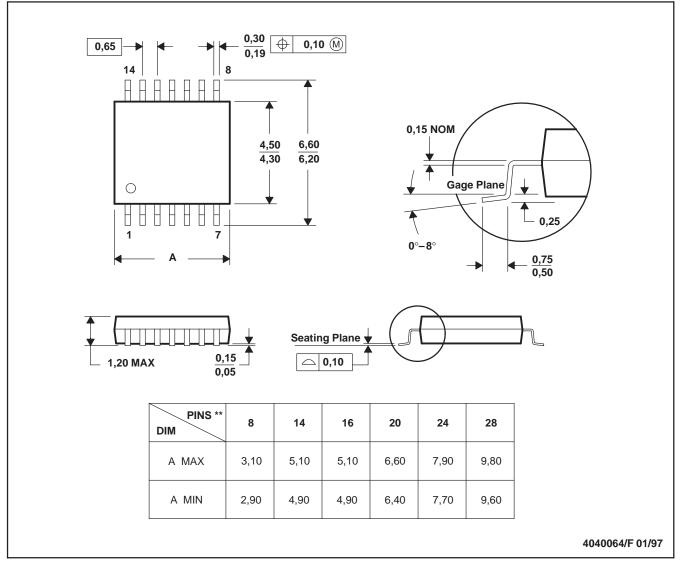
## **MECHANICAL DATA**

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

# PW (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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